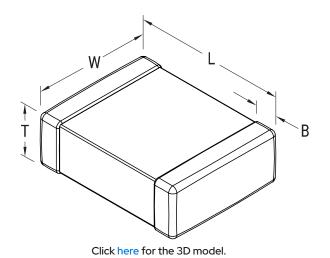


CBR04C319B2GAC

CBR-SMD RF COG, Ceramic, 3.1 pF, +/-0.1 pF, 200 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



| General Information | |
|--------------------------|---|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 1.37 mg |
| Notes | Solder Reflow Only. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|---------------------|
| Chip Size | 0402 |
| L | 1mm +/-0.05mm |
| W | 0.5mm +/-0.05mm |
| т | 0.5mm +/-0.05mm |
| В | 0.25mm +0.05/-0.1mm |

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 3.1 pF |
| Tolerance | +/-0.1 pF |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 462 |

Packaging Specifications Packaging

Packaging Quantity

T&R, 180mm, Plastic Tape 10000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.